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Article

Further Characterization of the Polycrystalline p-Type β -Ga₂O₃ Films Grown through Thermal Oxidation of GaN at 1000 to 1100 °C in N₂O Atmosphere

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Abstract: The development of good conductivity p-type β -Ga₂O₃ is critical to realize its devices and applications. The nitrogen-doped p-type β -Ga₂O₃ films with enhanced conductivity characteristics were prepared through the thermal oxidation of GaN in the N₂O atmosphere. Further measurements were performed on the oxidized films at 1000, 1050, and 1100 °C to have insight into the underlying mechanism of the thermally activated transformation process. The room temperature photoluminescence (PL) spectra demonstrated a moderate ultraviolet emission peak at 246 nm, confirming the generation of gallium oxide with a band gap of ~5.0 eV. The normalized X-ray diffraction (XRD), the high-resolution transmission electron microscopy (HRTEM), and the selected area electron diffraction (SAED) patterns were used to confirm the characteristic of polycrystalline and anisotropic growth. Then, the effects of the oxidation temperature on the amount of incorporated nitrogen were analyzed using secondary ion mass spectrometry (SIMS). Moreover, the ionization energy of the acceptor of films oxidized at 1000, 1050, and 1100 °C was calculated and analyzed using the temperature-dependent Hall test results. The results showed that nitrogen doping was the main contributor to p-type electrical properties. The activation energy of the polycrystalline β -Ga₂O₃ prepared through thermal oxidation of GaN in the N₂O atmosphere was estimated to be 147.175 kJ·mol⁻¹ using the Arrhenius plot, which was considerably lower than that of both dry and wet oxidations of GaN in O₂ ambient, thus confirming the efficiency of thermal oxidation of GaN in N₂O.

Keywords: gallium oxide; thermal oxidation; p-type conductivity; polycrystalline crystal

1. Introduction

Monoclinic β -Ga₂O₃, as the ultra-wide bandgap transparent semiconducting oxide, has attracted significant research focus [1–4]. Although having the notable thermal conductivity disadvantage, β -Ga₂O₃ currently has been used in the high power electronics, the kV-class Schottky barrier diodes [5–7], the e- and d-mode MOSFETs [8–10] and MESFETs [11], the solar-blind UV photodetectors [12,13], the light emitting diodes [14], sensing systems [15,16], solar cells [17], photocatalysts [18] and phosphors [19].

At present, bulk single crystals of β -Ga₂O₃ are grown through the Czochralski [20] and the EFG methods [21] with a reasonable size and structural quality. Moreover, high structural quality homo-epitaxial layers were obtained using MOVPE [22] and MBE [23]. The grown β -Ga₂O₃ can be either electrical insulators or n-type semiconductors. It can be grown via intentional doping with the electron concentration tunable between 10¹⁶ and 10¹⁹ cm⁻³, Hall electron conductivity ranging from 10⁻¹² to 10² S·cm⁻¹, and Hall electron mobility up to 170 cm²·V⁻¹·s⁻¹ [24–26]. However, the development of the improved p-type conductivity in β -Ga₂O₃ has not been effectively achieved. Therefore, the demand for further study on appropriate acceptor doping is necessary [27–29].

Nitrogen is one of the promising acceptor species for Ga₂O₃. For substituting O, nitrogen is the closest to O in terms of atomic size but has one less valence electron than O. Studies have been

conducted and reported on the generation of the p-type nitrogen-doped β -Ga₂O₃ films [30,31] and the nanowires [32,33] through thermal oxidation GaN in O₂ atmosphere at 1000 to 1100 °C. Moreover, our previous study demonstrated the successful growth of p-type nitrogen-doped β -Ga₂O₃ films using the low bond energy N₂O gas for the thermal oxidation of GaN [34]. Because N₂O can be easily decomposed into O atoms and 'N=N', it can effectively complete the oxidation substitution. Therefore, the p-type β -Ga₂O₃ films produced in the N₂O atmosphere have higher Hall hole concentration and higher conductivity than thermal oxidation of GaN with O₂ at the same temperature range.

The technology of nitrogen-doping for β -Ga₂O₃ needs to be explored in detail. Given the same experimental results presented in the previous study [34], this study focused on the analysis of the characteristics at 1000, 1050, and 1100 °C, in which the grown β -Ga₂O₃ achieved the Hall hole concentrations above $2.55 \times 10^{16} \text{ cm}^{-3}$. This study aimed to: (1) further corroborate the prepared films are polycrystalline β -Ga₂O₃ using PL, normalized XRD, HRTEM, and SAED; (2) explore the variations in nitrogen-doping concentration using secondary ion mass spectrometry (SIMS) within the oxidation temperature range; (3) determine the primary acceptor by analyzing the valence band spectrum and calculating the ionization energy of the acceptor; (4) explore the advantage of oxidation efficiency in N₂O atmosphere by calculating the activation energy. The activation energy in this study was 147.175 kJ·mol⁻¹. To our knowledge, the activation energies of dry and wet oxidations of GaN using oxygen were 300 kJ·mol⁻¹ [35] and 210 kJ·mol⁻¹ [36], respectively.

2. Experimental Procedure

The un-doped (native n-type with an electron concentration of $1.02 \times 10^{17} \text{ cm}^{-3}$) (0001) GaN wafers with 5.8-5.9 μm thickness were heated in a horizontal quartz tube furnace to 1000, 1050, and 1100 °C under N₂O gas at a flow rate of 200 cc·min⁻¹ for 60 min. More details of the experimental parameters can be found in [34].

A fluorescence spectrometer (PI-PLE-2355/2558+PIXIS-256E, Princeton Instruments) was used to measure the room temperature PL spectra using two different light sources at different wavelength ranges. The light source was obtained at a wavelength ranging from 242 to 300 nm by grating spectrophotometry. In addition, at a wavelength range of 325-700 nm, the light source was the 325 nm He-Cd laser.

Then the phase structure of the samples was identified with the normalized XRD (Malvern Panalytical EMPYREAN SERIES 3) using Cu K α ($\lambda = 1.54 \text{ \AA}$) X-ray source at a 2-theta range of 10 to 80° using a sampling pitch and preset time of 0.02° and 0.24 s, respectively.

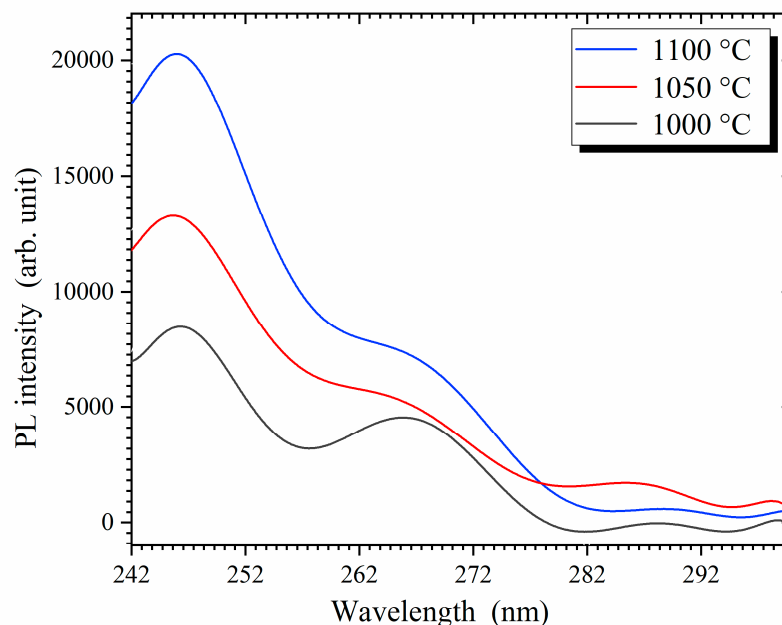
Transmission electron microscopy (TEM) on Talos F200X S/TEM at 200 kV was used to determine the oxide thickness and analyze the cross-sectional microstructure. The cross-sectional specimens were prepared using focused ion beam (FIB) milling (Helios-5UX), and the phases and lattice structure were further investigated using HRTEM and SAED.

The depth profiles of Ga, O, and N in the films oxide at 1000, 1050, and 1100 °C were qualitatively analyzed using SIMS (TOF.SIMS5-100). During SIMS measurements, the secondary ions were detected using 5 keV Cs⁺ bombardment at an incidence angle of 60° to distribute ions. X-ray photoelectron spectroscopy (XPS, ThermoFisher ESCALAB Xi+) was used to investigate the valence band characteristic of β -Ga₂O₃. Before the XPS measurement, the applied voltage of 15 kV accelerated the Ar ion beam at a sputtering rate of 0.10 nm·s⁻¹ for 100 s to etch 10 nm depth into the samples. The XPS analysis revealed the valence band characteristic on the β -Ga₂O₃ layer. Moreover, the XPS analysis further confirmed the variation in the N-doping ratio and Ga/O ratio with oxidation temperature.

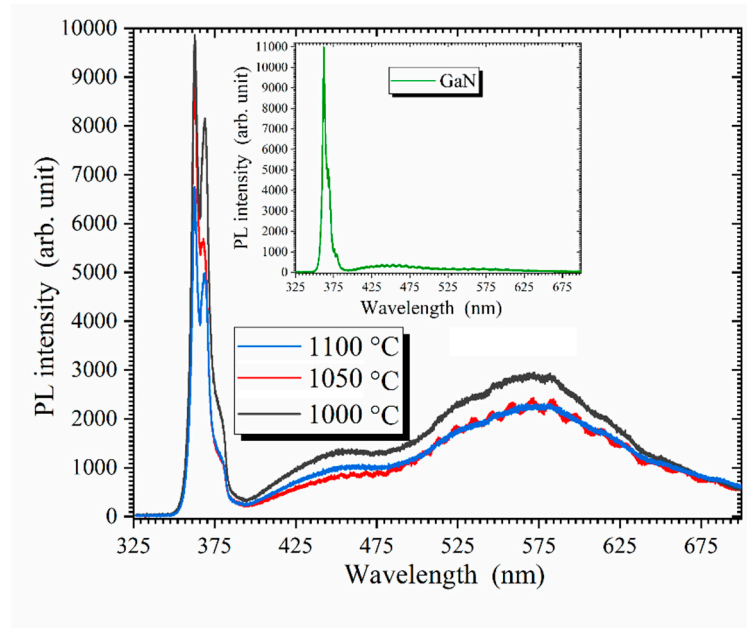
Indium electrodes were sputtered on the films, followed by rapid thermal annealing (RTA) at 600 °C for 60 s to form a good ohmic contact. Given the electrical property test results using the temperature-dependent (70 to 540K) Rmagnetic-field-dependent Van der Pauw Hall effect measurements (PPMS DynaCool-9) under a vacuum test environment, the acceptor ionization energies were calculated from the linear regression formula of $\ln(p)$ versus $1000/T$.

3. Results and discussion

The room temperature PL spectrum measurements were conducted to determine the nature of the grown films as a function of the oxidation temperature. Figure 1a depicts the PL spectra (at a wavelength ranging from 242 to 300 nm) of the samples obtained through thermal oxidation at 1000, 1050, and 1100 °C. Although the light source by grating spectrophotometry was weak, a fairly distinct emission peak around 246 nm (~ 5.0 eV) was observed in all grown films. The observed emission peak was attributed to the band-to-band luminescence of gallium oxide, confirming that Ga_2O_3 was successfully produced through the thermal oxidation of GaN. Moreover, the peak intensity around 246 nm increased 2.6 times, and the full width at half-maximum significantly decreased with increasing oxidation temperature, indicating that the oxide layer became thicker. Figure 1b and its inset show the PL spectra of the oxidation films and the un-doped commercial GaN substrate within the wavelength range of 325-700 nm for comparison using the 325 nm He-Cd laser as a light source. The emission peaks at 355 nm (~ 3.491 eV) and 366 nm (~ 3.387 eV) belonged to GaN [37]. As the temperature of thermal oxidation increased, these two emission peaks of GaN decreased. Besides, comparing with the PL from the GaN substrate, the yellow emission at 565 nm (~ 2.194 eV) in the oxide films was ascribed to the Ga vacancies during high-temperature growth [38,39].



(a)



(b)

Figure 1. (a) PL emission spectra of the thermally oxidized samples at 1000, 1050, and 1100 °C within the wavelength range of 242–300 nm at room temperature. The emission was excited using grating spectrophotometry. **(b)** PL emission spectra of the thermally oxidized samples at 1000, 1050, and 1100 °C within the wavelength range of 325–700 nm at room temperature. The inserted image is the PL spectrum of the undoped GaN substrate. The emission was excited using a 325-nm He-Cd laser.

The XRD patterns of the grown films as a function of the oxidation temperature confirmed the formation of the β -Ga₂O₃ phase with a preferred orientation along the $\{201\}$ directions. The XRD results were compared with the standard powder diffraction files of PDF# 43-1013 for β -Ga₂O₃ and PDF# 50-0792 for GaN. As shown in Figure 2, to compensate for the impact of large differences in oxidation depth on the corresponding intensity of XRD, each diffraction peak was normalized by the highest diffraction peak from the most preferred orientation at the same oxidation temperature. When the oxidation temperature was between 1000 and 1050 °C, the most preferred orientation was $(\bar{2}01)$ located at 18.7°. Then, at 1100 °C, the most preferred orientation was $(\bar{4}02)$ located at 38.2°. In addition to the $\{201\}$ family of planes at 18.7°, 38.2°, and 59.1°, there were relatively strong diffraction peaks belonging to $\{400\}$, (002) , $(\bar{1}12)$, and (020) phases of β -Ga₂O₃, indicating that the β -Ga₂O₃ thin film obtained through high-temperature thermal oxidation was polycrystalline.

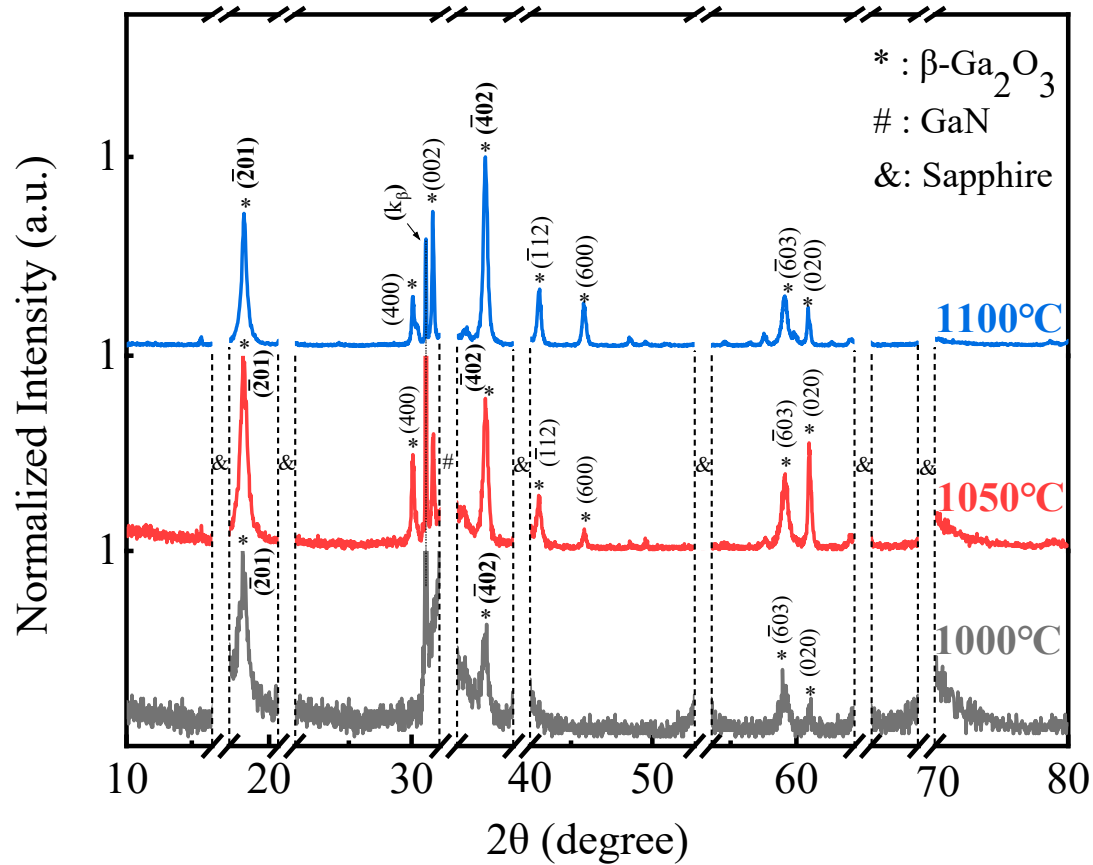


Figure 2. Normalized XRD patterns of thermally oxidized samples at 1000, 1050, and 1100 °C compared with ICDD file PDF# 43-1013 for β -Ga₂O₃ and PDF# 50-0792 for GaN.

The SAED pattern of a detailed characterization of the grown β -Ga₂O₃ film is shown in Figure 3a–c. The discrete bright spots belonged to the (201), (402), (002), (111), (020), and (400) crystal planes of β -Ga₂O₃, further demonstrating the polycrystalline nature of the β -Ga₂O₃ thin film. Additionally, for the sample thermally oxidized at 1000, 1050, and 1100 °C, the enlarged HRTEM images (Figure 3d–f) of the region around the β -Ga₂O₃/GaN interface displayed a clear boundary between the β -Ga₂O₃ film and the GaN substrate without transition zone. Moreover, the crystal plane orientations of the β -Ga₂O₃ thin film in HRTEM images ulteriorly confirmed the polycrystalline nature of the β -Ga₂O₃ thin film.

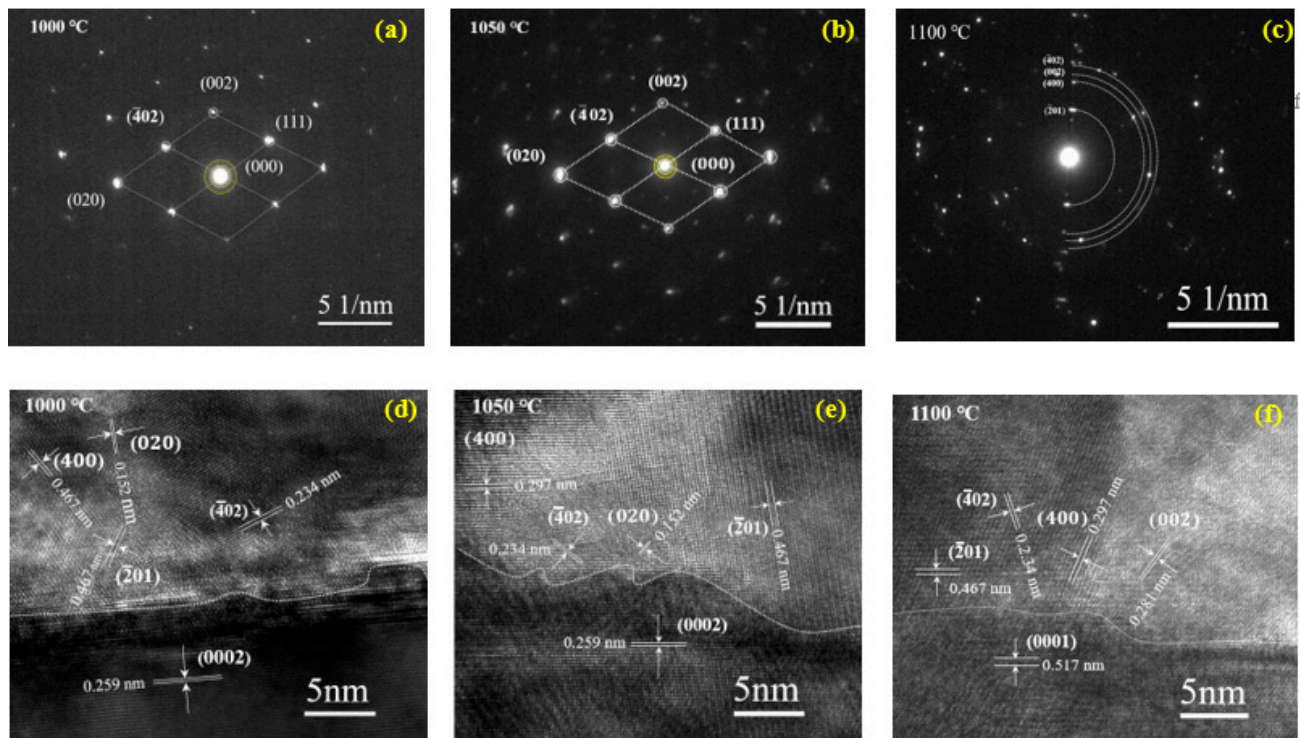


Figure 3. The SEAD patterns of the β -Ga₂O₃ layer grown at (a) 1000 °C, (b) 1050 °C, and (c) 1100 °C, and the corresponding HRTEM images taken from the β -Ga₂O₃/GaN interface of the thermally oxidized samples (d) 1000 °C, (e) 1050 °C, and (f) 1100 °C.

For the samples thermally oxidized at 900, 950, 1000, 1050, and 1100 °C, the natural logarithm plot of the oxide layer thickness ($\ln(\text{Thickness})$) as the function of oxidation temperature ($1000/T$) is cumulatively plotted in Figure 4. Based on the oxidation thickness, the activation energy required for thermal oxidation (0001) of monocrystalline GaN to form polycrystalline β -Ga₂O₃ in the N₂O atmosphere was analyzed. The Arrhenius equation described the temperature dependence of chemical reactions better. Therefore, the activation energy was calculated using the idealized Arrhenius law behavior shown in equation (1) according to our experiments of thermal oxidation of GaN in the N₂O atmosphere at 900 to 1100 °C:

$$\ln(\text{Thickness}) = \ln(\text{Thickness}_0) - \frac{E_{\text{activation_energy}}}{k * T} \quad (1)$$

where k is the Boltzmann constant; Thickness_0 is the thickness of β -Ga₂O₃ at 900 °C [34], taking as the initial thickness of the oxidation process; T is oxidation temperature in Kelvin. The activation energy calculated from equation (1) was approximately 147.175 kJ·mol⁻¹. In the previous studies, the reported results of activation energies of dry and wet thermal oxidations of GaN in O₂ ambient were 300 [35] and 210 kJ·mol⁻¹ [36], respectively. This result quantitatively shows that the O atom in the low bond energy under the N₂O atmosphere can easily get free from the covalent bond at the same temperature. As a result, the oxidation rate was relatively fast, and the activation energy required was relatively low.

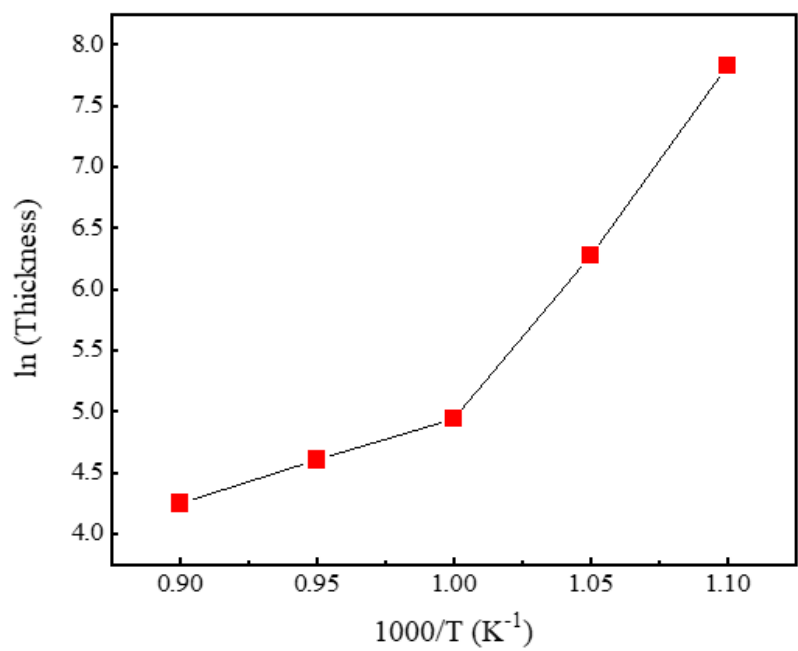


Figure 4. The natural logarithm plot of the oxide layer thickness (ln (Thickness)) as the function of oxidation temperature (1000/T) for the thermally oxidized samples at 900, 950, 1000, 1050, and 1100 °C.

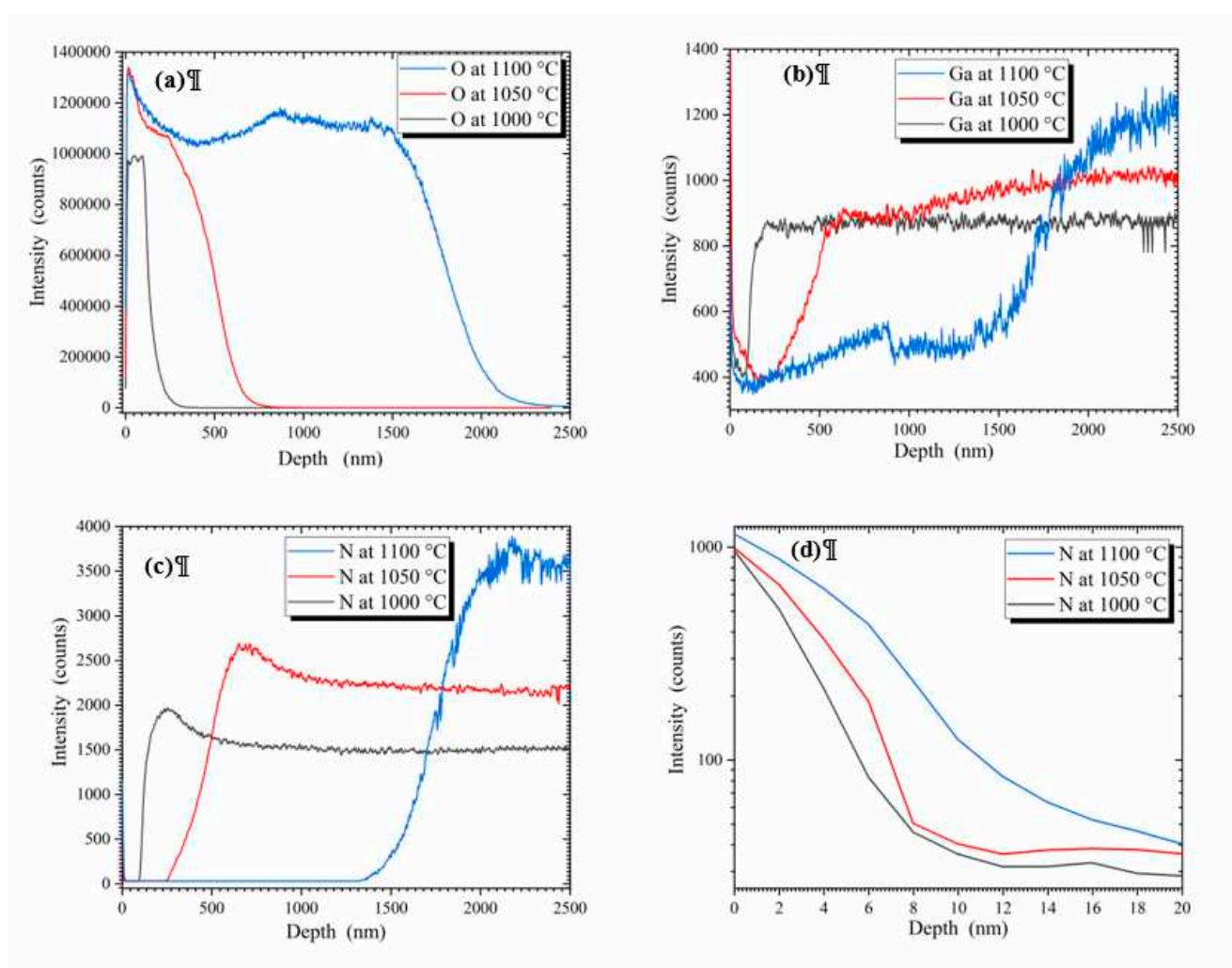


Figure 5. SIMS characterizations of the depth profiles of (a) O, (b) Ga, (c) N from 0 to 2.5 μm depth for the thermally oxidized samples at 1000, 1050, and 1100 $^{\circ}\text{C}$. (d) The enlarged view of the N with a depth of 0-20 nm.

In Figure 6a–c, for the samples thermally oxidized at 1000, 1050 and 1100 $^{\circ}\text{C}$, the O, Ga, and N elemental's vertical distributions from SIMS were exhibited. The depth of the analysis includes the topmost surface layer to the depth of 2.5 μm . Figure 6a shows the O ion response intensities of the SIMS test as a function of depth. The thickness of $\beta\text{-Ga}_2\text{O}_3$ films at 1000, 1050, and 1100 $^{\circ}\text{C}$ to be 145 nm, 530 nm, and 2.5 μm , respectively. These results were consistent with the longitudinal distribution depth of O in SIMS results (Figure 6a). As shown in Figure 6a, within the $\beta\text{-Ga}_2\text{O}_3$ layer, the O content gradually reduced in the downward direction approaching the $\beta\text{-Ga}_2\text{O}_3/\text{GaN}$ interface. At all three oxidation temperatures, the higher the oxidation temperature, the higher the reduction of O content when approaching the interface. The main reason for the insufficient O was that the N atoms in the underlying GaN were separated by thermal oxidation and gradually moved upward; thus, in the $\beta\text{-Ga}_2\text{O}_3$ layer, N replaced O to form the N-doped $\beta\text{-Ga}_2\text{O}_3$. Moreover, the N was more abundant close to the interface; as a result, it substituted more O, thus decreasing O content. In addition, at a higher temperature, the O in the $\beta\text{-Ga}_2\text{O}_3$ is more likely to be released from the covalent bond and escape from the polycrystalline $\beta\text{-Ga}_2\text{O}_3$ layer. Therefore, O vacancies existed in the grown $\beta\text{-Ga}_2\text{O}_3$ layer. Figure 6b shows the Ga ion response intensities of the SIMS test as a function of depth. In the grown $\beta\text{-Ga}_2\text{O}_3$ layer, the stoichiometric ratio of Ga:O is 2:3. In the GaN substrate, the stoichiometric ratio of Ga:N 1:1. The test mode of SIMS in this study was based on the relative content ratio of elements. As shown in Figures 6a and 6b, the content of Ga was relatively low within the range of the depth of the corresponding $\beta\text{-Ga}_2\text{O}_3$ layer. The content of Ga was relatively high in the depth range of the

corresponding GaN layer. Moreover, the depth position of the change in Ga content was consistent with the observed oxidation thickness of FIB, indicating that the β -Ga₂O₃ layer was indeed successfully oxidized. As shown in Figure 6b, the Ga content close to the top of the β -Ga₂O₃ was lower than that of the stoichiometric β -Ga₂O₃, indicating that Ga vacancies were formed by the high-temperature oxidation close to the β -Ga₂O₃ surface. Figure 6c shows the N ion response intensities as a function of depth obtained from the SIMS test. As shown in Figure 6c, the position where the N content became stable corresponded to the interface position between the β -Ga₂O₃ and the GaN layer. Moreover, the portion of N within the β -Ga₂O₃ region decomposed from GaN and transmitted to the β -Ga₂O₃ layer above it, increasing the relative N concentration. In the β -Ga₂O₃ layer, the lower the position close to the GaN layer, the higher the N-doping concentration. However, further away from the GaN layer, the N-doping decreased. To interpret the effect of N atoms separated from N₂O on N-doping in the β -Ga₂O₃ layer, Figure 6d shows an enlarged view of the N from 0 to 20 nm depth of the thermally oxidized samples at 1000, 1050, and 1100 °C. Although the decomposed N from N₂O also participated in the N-doping, the doping depth was relatively shallow, and the doping concentration was low at a depth of 20 nm. The N-O bond in N₂O was a single bond with low bond energy; thus, the O atom was easily separated at high temperatures. In contrast, the two N atoms in N₂O were double-bonded. Consequently, high bond energy was required to break the two double-bonded N atoms, meaning that the proportion of N separated at high temperatures was relatively low. As shown in Figure 6c,d, the decomposed N from GaN was the main source of N-doping in grown β -Ga₂O₃.

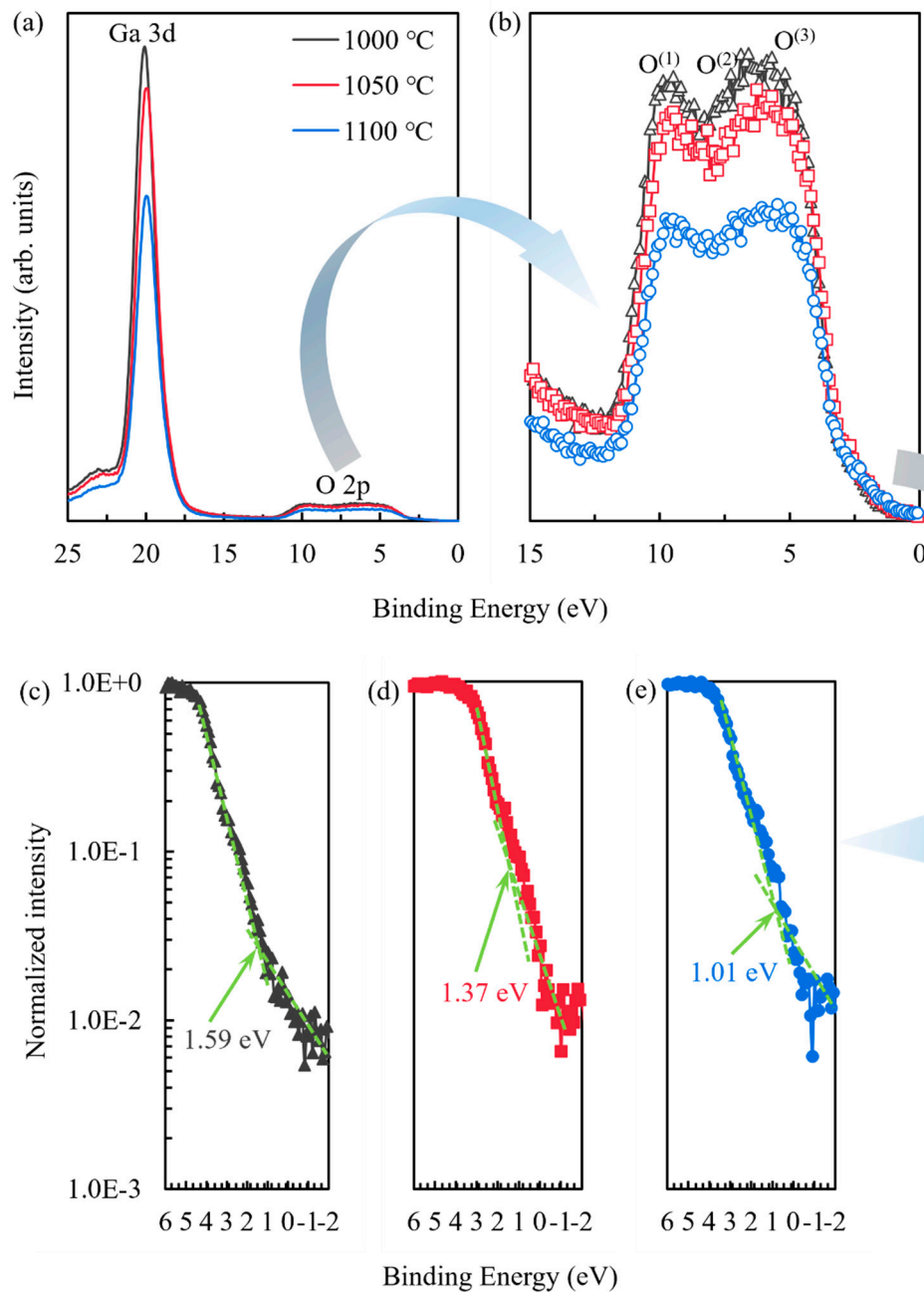


Figure 6. (a) X-ray photoelectron spectroscopy of the β -Ga₂O₃ valence band for the thermally oxidized samples at 1000, 1050, and 1100 °C (calibrated with respect to Ga 3d). (b) A zoom of the valence band region for the O 2p characteristic peak. Further investigation of the tail states of the valence band for the thermally oxidized samples at (c) 1000 °C, (d) 1050 °C, and (e) 1100 °C.

To further support the relative proportions of elements observed during the SIMS tests, the elemental ratios of N and the Ga/O observed using XPS are presented in Table 1. According to the stoichiometric ratio (Ga/O is ~ 0.6667), the polycrystalline β -Ga₂O₃ grown through thermal oxidation always exhibited an O-deficient state in the Ga/O ratio (Table 1). In the process of oxidation, although O vacancies were formed, the key reason for O deficiency was that N replaced O rather than O vacancies. Moreover, as the oxidation temperature increased, the proportion of G decreased slightly, implied that the Ga vacancies increased slightly with the increase of oxidation temperature. In addition, as oxidation temperature increased, the proportion of N in the β -Ga₂O₃ layer increased. This result is consistent with that of N response intensities in SIMS. It also confirms that the p-type conductivity of the films improves with the increase in oxidation temperature.

Table 1. The elemental ratio of N and Ga/O ratio values from XPS.

Oxidation temperature (°C)	1000	1050	1100
Ga/O ratio	0.831	0.821	0.818
N elemental ratio (%)	0.0323	0.0369	0.0878

XPS was used to investigate the valence band characteristic of the thermally oxidized samples at 1000, 1050, and 1100 °C (Figure 7a–e). Both theoretical studies [40,41] and experimental results [42,43] have demonstrated that the density of states for the valence band is predominated by the O 2p character. And the Ga 3d peak was used as the calibration peak. As the oxidation temperature went up, the valence band edge of O 2p shifted further to the right, and the moved valence band (Figure 7a,b) accordingly, indicating a lower Fermi level and more p-type characteristic. Figure 7c–e show the enlarged tail parts of the valence band for the thermally oxidized samples at 1000, 1050, and 1100 °C, respectively. The ordinates of Figure 7c–e, counts per second (counts/s), are normalized to the maximum value ranging from 0 to 5 eV. The variation trend of the slope at the turning point of the tail confirmed the presence of states in the lower part of the bandgap. As the oxidation temperature increased, the shallow acceptor levels introduced by N-doping moved closer toward the valence band, indicating a larger p-type carrier density, thus improving p-type conductivity.

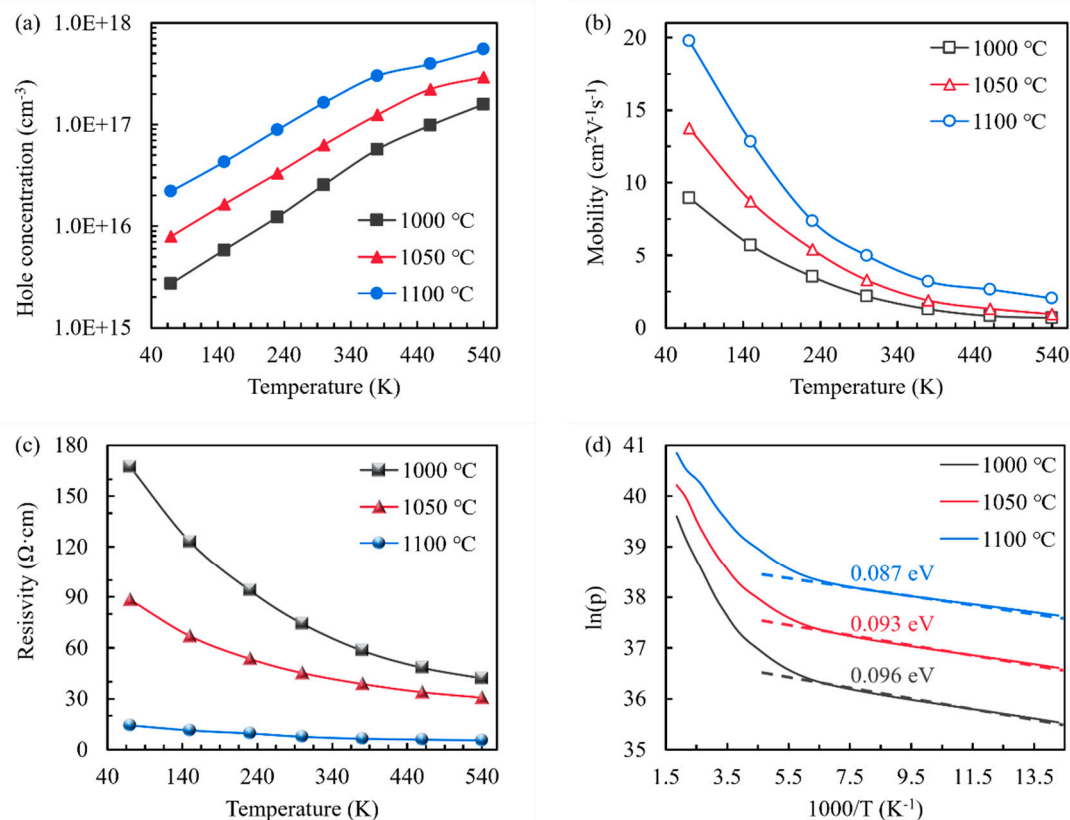


Figure 7. For the thermally oxidized samples at 1000, 1050, and 1100 °C, the variations in (a) Hall hole concentration, (b) Hall hole mobility, and (c) Hall resistivity as a function of the test temperature. (d) The natural logarithm plot of Hall hole concentration ($\ln(p)$) as the function of ($1000/T$).

The temperature-dependent Hall measurements were conducted (from 70 to 540 K) on the samples oxidized at 1000, 1050, and 1100 °C under a vacuum environment. The positive Hall coefficients confirmed that the N-doped $\beta\text{-Ga}_2\text{O}_3$ films were p-type. The variations in Hall hole concentration, Hall hole mobility, and Hall resistivity of samples as the function of the test temperature are highlighted in Figure 7a–c, respectively. In addition, the natural logarithm plot of Hall hole concentration ($\ln(p)$) as the function of ($1000/T$) is shown in Figure 7d. With the increase in

test temperature, the changes in Hall hole concentration, Hall mobility, and Hall resistivity of the three samples were consistent and showed a reasonable trend. As the test temperature increased from 70 to 540 K, Hall carrier concentration increased, whereas Hall mobility and Hall resistivity decreased. Under the same test temperature, the higher the oxidation temperature, the more N-doping in the β -Ga₂O layer formed through oxidation, thus contributing higher Hall hole concentration, better Hall mobility, and smaller Hall resistivity. At a test temperature of 300 K, the Hall hole concentrations of the three samples were $2.55 \times 10^{16} \text{ cm}^{-3}$ (@1000 °C oxidation temperature), $6.31 \times 10^{16} \text{ cm}^{-3}$ (@1050 °C oxidation temperature), and $1.63693 \times 10^{17} \text{ cm}^{-3}$ (@1100 °C oxidation temperature). PL and SIMS results showed that Ga and O vacancies existed in β -Ga₂O films obtained through high-temperature oxidation. V_{Ga} and the pairs of $V_{\text{Ga}}\text{-}V_{\text{O}}$ might act as potential acceptors [44–46]. However, based on the near-band-edge structure of β -Ga₂O₃ nanostrips depicted in Figure 7 of [47], the transition energy of the acceptor level $V_{\text{Ga}} \sim 0.494 \text{ eV}$ ($E_0 - E_{\text{D1}}$) [47]. At 300 K, this order of magnitude ionization energy can only contribute near 10^{15} order of magnitude for hole concentration. Therefore, the Hall hole concentration ranging from 2.55×10^{16} to $1.63693 \times 10^{17} \text{ cm}^{-3}$ was mainly contributed by N-doping in β -Ga₂O₃. β -Ga₂O₃ thin films with fairly good Hall hole concentration were obtained through oxidation technology. The carrier concentration increased in proportion to oxidation temperature. However, although the mobility also increased with the rise of oxidation temperature, the increase of mobility was not that much. (Figure 2b). This phenomenon was because when the oxidation temperature increased from 1000 to 1100 °C, more loose hollows were generated inside the cross-section of the β -Ga₂O₃ film. As a result, the defects and dangling bonds were introduced near the hollows, which in turn hindered the improvement of mobility. Therefore, no significant increase was observed in overall mobility. At a test temperature of 300 K, the Hall hole mobilities were $2.2 \text{ cm}^2\text{V}^{-1}\text{s}^{-1}$ (@1000 °C oxidation temperature), $3.3 \text{ cm}^2\text{V}^{-1}\text{s}^{-1}$ (@1050 °C oxidation temperature), and $5 \text{ cm}^2\text{V}^{-1}\text{s}^{-1}$ (@1100 °C oxidation temperature). Similarly, the Hall resistivity slightly decreased. At a test temperature of 300 K, the Hall hole motilities are $74 \text{ }\Omega\text{-cm}$ (@1000 °C oxidation temperature), $45 \text{ }\Omega\text{-cm}$ (@1050 °C oxidation temperature), and $7.7 \text{ }\Omega\text{-cm}$ (@1100 °C oxidation temperature). Figure 7d displays the natural logarithm plot of Hall hole concentration ($\ln(p)$) as the function of $(1000/T)$. Based on the linear regression formula of $\ln(p)$ versus $1000/T$, the acceptor ionization energies of oxidized samples at 1000, 1050, and 1100 °C were similar, which were $\sim 0.092 \pm 0.005 \text{ eV}$. The smaller acceptor ionization energy implies the easier hole activation of the N-doping instead of Ga vacancies for the β -Ga₂O₃ film. This phenomenon further demonstrates that N-doping mainly contributes to p-type electrical conductivity.

4. Conclusion

Nitrogen-doping acceptor in β -Ga₂O₃ with Hall hole concentration ranging from $2.55 \times 10^{16} \text{ cm}^{-3}$ to $1.63693 \times 10^{17} \text{ cm}^{-3}$ was realized through thermal oxidation of GaN in N₂O atmosphere at temperatures of 1000 to 1100 °C. The structural analysis using PL, normalized XRD, and FIB-TEM confirmed that grown β -Ga₂O₃ films were polycrystalline. The calculation of activation energy based on oxidation thickness confirmed that the process of thermal oxidation and nitrogen-doping in the N₂O atmosphere was more efficient than that in an oxygen atmosphere. Finally, the analysis of the valence band energy spectrum and Hall electrical property revealed that the p-type conductivity of the polycrystalline β -Ga₂O₃ was mainly realized by substituting O in β -Ga₂O₃ with N.

Author Contributions: Sufen Wei designed the experimental and test schemes, organized the data, and wrote the paper; Yi Liu performed the experiments and analyzed the data and measurements; Qianqian Shi and Tinglin He analyzed the data and measurements; Feng Shi helped with analyzing the basic principles and writing the paper; and Ming-Kwei Lee put forward the idea of experiment, guided the analysis of the experimental results, and helped with editing the English.

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